

SURFACE ANALYSIS LAB

The Surface Analysis Laboratory,
located in the Department of Physics,
houses a X-ray Photoelectron Spectroscopy system (XPS)
and a Scanning Auger Microscopy and Spectroscopy system (SAM/AES).
The system enables quantitative elemental identification
and analysis of the surface chemical state
with depth information just a few nanometers.
It also has the possibility of surface etching by an argon ion source
and a depth profiling chemical analysis.
Also XPS imaging allows
the mapping of the chemistry of the surface,
with spatial resolution of a few microns.

Application Field

- 1. Nanotechnology (highly complex nanostructures)
 - 2. Catalytic and Petrochemical (active surfaces)
- **3**. Coating, Thin Film technology and heterostructures (surface-interface and quantitative analysis)
 - 4. Biomaterials
 - 5. Organic and polymeric materials

Services Offered to Third Parties

- 1. Extensive surface and depth profilling study
- 2. Chemical analysis of high technology samples
- 3. High demanding systems and composites analysis
- 4. Provision of analytical reports, audited by a scientific leader.

Surface Analysis Lab

Head of the Laboratory

Konstantinos Chrissafis, Professor

Members of the Lab/Research Team

G. Vourlias, Assoc. Professor
P. Patsalas, Professor
D. Karfaridis, PhD student
N. Pliatsikas, PhD
A. Teknetzi, Phd student

Contact

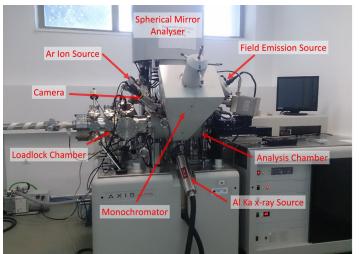




Figure 1 Left: AXIS UltraDLD X-ray Photoelectron Spectroscopy (XPS) and Scanning Auger Microscopy and Spectroscopy System (SAM/AES) by Kratos Analytical. Right: Back view of the system on the side of the load-lock chamber and of the Ar+ Ion Source. The cluster equips the Surface Analysis Laboratory located in the Department of Physics. The main parts are marked in the figure with the corresponding arrows.

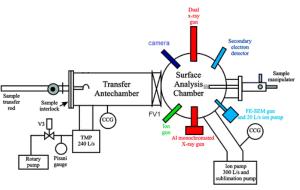


Figure 2 Schematic representation of the cluster's view. The cluster is composed of two chambers; The load-lock (left) chamber and the main analysis chamber (right). Distinguish the AI monochromatic X-ray gun, the rear dual X-ray source, the Ar+ ion gun and the Electron source and detector.

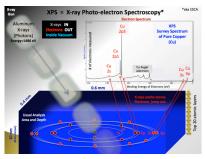


Figure 3 The Photoelectric Effect using as an excitation source an Al-Ka, X-ray anode and an electron spectrum (widescan) obtained from a measurement showing the XPS peaks from the surface's elements.

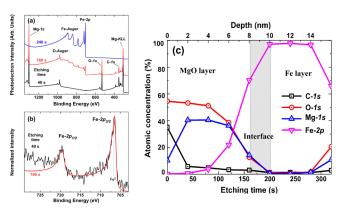


Figure 4 XPS measurements with etching process (etching rate $\sim 0.38 \text{ Å/sec}$) on MgO(10nm)/Fe(6nm) thin bilayers. (a) Representative widescan spectra in 3 different depths from the initial surface. (b) Indicative high resolution (HR) XPS peaks from the Fe-2p orbitals during the etching process. (c) Diagram of the percentage elementary concentration as a function of the analysis depth. XPS depth profiling proved the existence of a sharp interface between the layers.

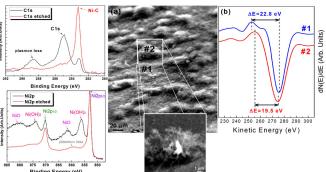


Figure 5 HR XPS measurements of nanocomposite catalysis of DLC:Ni for the growth of carbon nanotubes (CNTs) before and after the Ar+ ion etching of the surface. FEG AES measurements and quality tests of CNTs carried out from two different spots as shown in the SAM images. Spot #1 indicates CNTs of excellent quality because of the nano-scale Ni particles presence as substrate for the growth of CNTs. Spot #2, on the other hand, shows CNTs of bad quality.the layers.

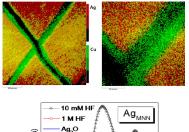


Figure 6
Upper figure: XPS imaging technique for the examination of the component allocation on the surface of a self-patterned Ag-Cu sample. The color matching reveals the concentration of each material in 2D as recorded.
Lower figure: Observation of the oxidation states of Ag plasmonic NPs by means of XAES, through a 4-profile deconvolution peak analysis.